

REMARKS

Reconsideration of this application in light of the amendments and arguments herein is respectfully requested.

I. Status of the Claims

Claims 1 and 5 have been amended and the amendments do not add new matter.

Claims 7-9 have been added and no new matter is added.

Claims 1-9 are pending.

II. Rejections under 35 U.S.C. §§ 102 and 103

Claims 1-4 stand rejected under 35 U.S.C. § 102(b) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over Flip Chip Technologies. Claims 2, 3, 5, and 6 are rejected under 35 U.S.C. § 103(a) as unpatentable over Flip Chip Technologies in view of U.S. Patent No. 5,965,064 to Yamada et al. ("Yamada") The Examiner states that Flip Chip Technologies discloses flip chip bonding methods using conductive particles and the conductive particle mounting processes. Further, the Examiner states that Yamada discloses bumps and pads. Applicants respectfully traverse the rejections for the following reasons.

Claim 1 has been amended to recite that "a portion of the particles have a shape of a ball and another portion of the particles have a shape of a cube." In contrast, Flip Chip Technologies does not disclose or suggest the shape of the conductive particles. Further, all of the conductive particles disclosed by Flip Chip in Figures 10.8-10.12 all have a round shape. Therefore, Applicants respectfully submit that Flip Chip Technologies does not teach or suggest all the elements of the

claimed invention and that independent claim 1 is novel and non-obvious. Additionally, Yamada does not teach or suggest the elements missing from Flip Chip Technologies. Insofar as claims 2-6 depend from claim 1, Applicants submit that these claims are also allowable.

Regarding new claim 7, neither Flip Chip Technologies nor Yamada teaches or suggests “the fourth conjunction portion being higher than the third conjunction portion ” and “the particles between the second and fourth conjunction portions embedded in the fourth conjunction portion and the particles between the first and third conjunction portions uniformly bridged therebetween to compensate a height difference between the third conjunction portion and the fourth conjunction portion”.

Regarding new claim 9, neither Flip Chip Technologies nor Yamada teaches or suggests “a height difference being between the second group of conjunction portions” and “a part of the particles embedded in the second group conjunction portions to compensate the height difference therebetween”.

Therefore, Applicants submit that independent claims 7 and 9 are novel and non-obvious. Insofar as claim 8 depends from claim 7, the claim is allowable based at least on its dependency.


CONCLUSION

Withdrawal of the rejections and allowance of the claims, as now amended, are respectfully requested. Applicants have made every effort to place the present application in condition for allowance. It is therefore earnestly requested that the present application, as a whole, receive favorable consideration and that all of the claims be allowed in their present form.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

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Respectfully submitted

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